

HAT2088R

Silicon N Channel MOS FET High Speed Power Switching

REJ03G1183-0200

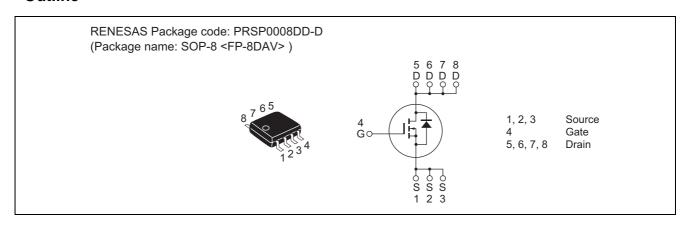
(Previous: ADE-208-1234)

Rev.2.00 Sep 07, 2005

Features

- Low on-resistance
- Low leakage current
- High density mounting

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Drain to source voltage	V_{DSS}	200	V
Gate to source voltage	V_{GSS}	±30	V
Drain current	I _D	2	Α
Drain peak current	I _{D (pulse)} Note 1	16	Α
Body-drain diode reverse drain current	I _{DR}	2	Α
Channel dissipation	Pch Note 2	2.5	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. When using the glass epoxy board (FR4 $40\times40\times1.6$ mm), PW ≤10 s

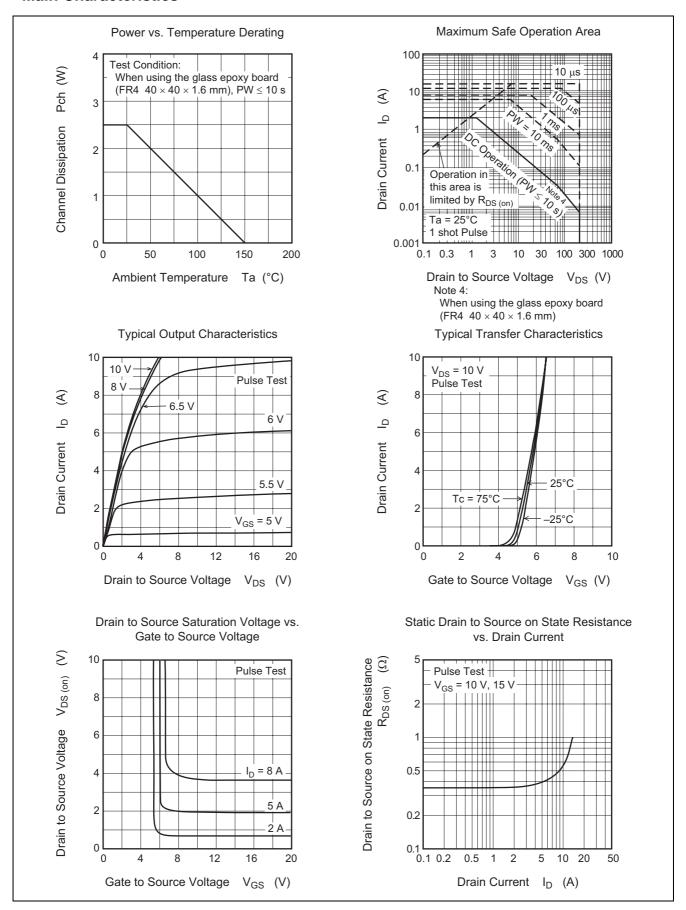
Electrical Characteristics

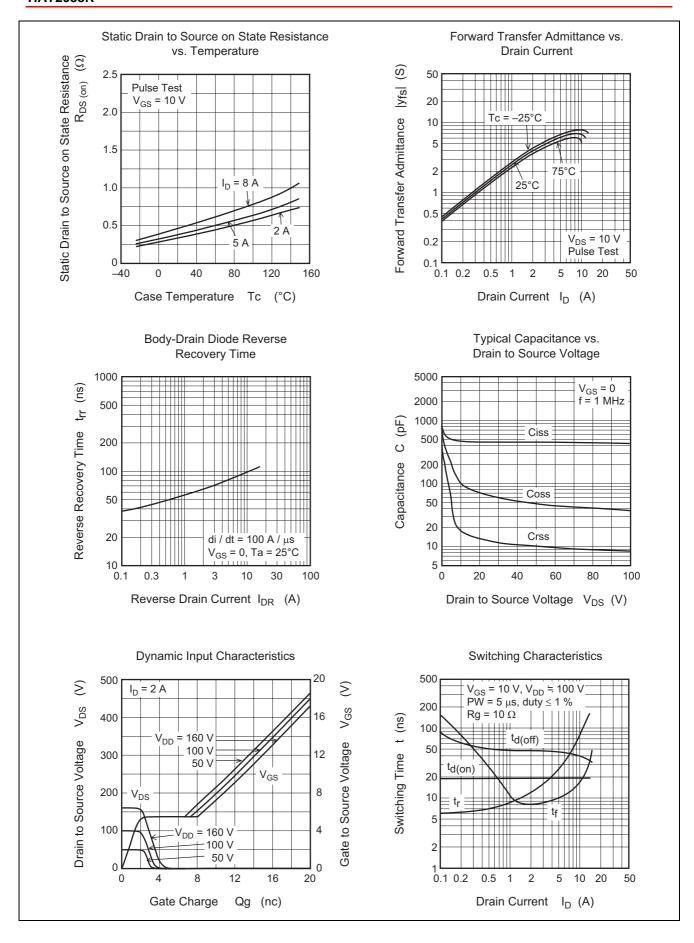
 $(Ta = 25^{\circ}C)$

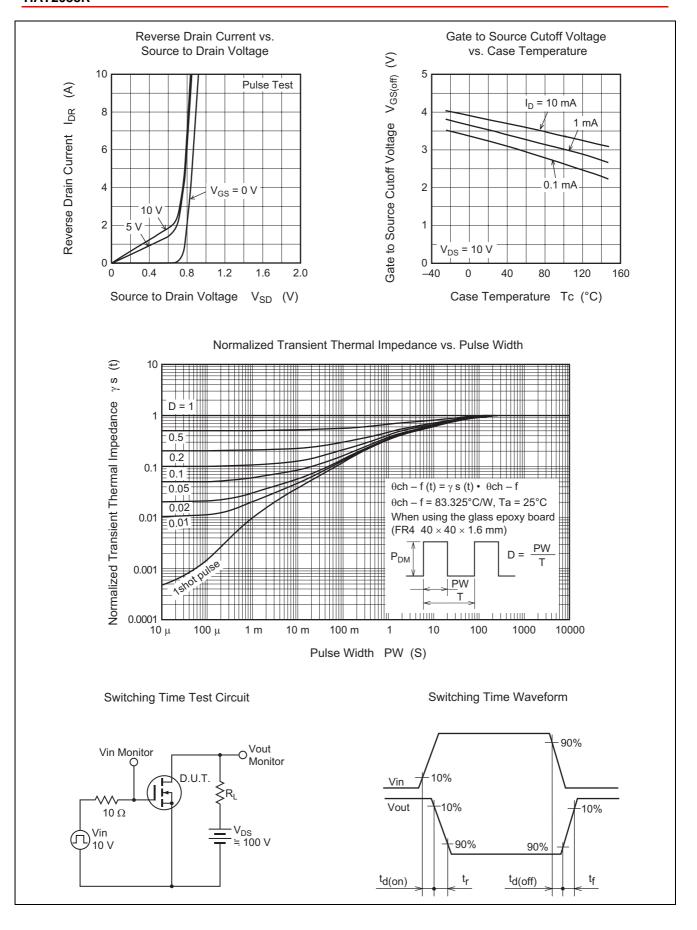
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	V (BR) DSS	200	_	_	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source leak current	I _{GSS}		_	±0.1	μΑ	$V_{GS} = \pm 30 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}		_	1	μΑ	$V_{DS} = 200 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	V _{GS (off)}	3.0	_	4.5	V	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$
Static drain to source on state resistance	R _{DS (on)}		0.35	0.44	Ω	$I_D = 1 \text{ A}, V_{GS} = 10 \text{ V}^{\text{Note 3}}$
Forward transfer admittance	y _{fs}	1.5	2.5	_	S	$I_D = 1 \text{ A}, V_{DS} = 10 \text{ V}^{\text{Note 3}}$
Input capacitance	Ciss	_	450	_	pF	$V_{DS} = 25 \text{ V}, V_{GS} = 0$
Output capacitance	Coss	_	65	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	13	_	pF	
Total gate charge	Qg	_	13	_	nC	V _{DD} = 160 V
Gate to source charge	Qgs	_	2	_	nC	V _{GS} = 10 V
Gate to drain charge	Qgd	_	6	_	nC	$I_D = 2 A$
Turn-on delay time	t _{d (on)}	_	19	_	ns	$V_{GS} = 10 \text{ V}, I_{D} = 1 \text{ A}$
Rise time	t _r	_	8.5	_	ns	$V_{DD} \cong 100 \text{ V}$
Turn-off delay time	t _{d (off)}	_	48	_	ns	$R_L = 100 \Omega$
Fall time	t _f	_	11	_	ns	$Rg = 10 \Omega$
Body-drain diode forward voltage	V_{DF}	_	0.8	1.2	V	$I_F = 2 \text{ A}, V_{GS} = 0$ Note 3
Body-drain diode reverse recovery time	t _{rr}	_	65	_	ns	$I_F = 2 A, V_{GS} = 0$
						di _F /dt = 100 A/μs

Note: 3. Pulse test

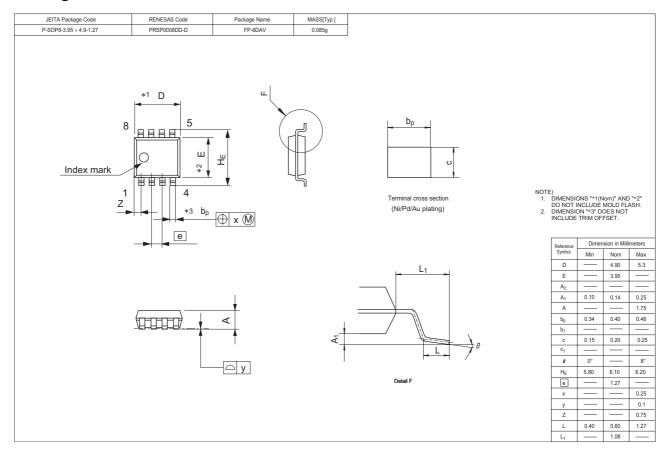
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT2088R-EL-E	2500 pcs	Taping

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